



IN THE U.S. PATENT AND TRADEMARK OFFICE

May 12, 2011

Applicants: Toshihiro TAI et al

Title: PLATED RESIN MOLDED ARTICLES

Serial No.: 10/586 378

Group: 1787

Confirmation No.: 2951

Filed: July 14, 2006

Examiner: Kruer

International Application No.: PCT/JP2005/002827

International Filing Date: February 16, 2005

Atty. Docket No.: 3400.P1434US

Mail Stop AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Herewith is an amendment in the above-identified application.

☐ Applicant claims small entity status. See 37 CFR 1.27.

☐ The additional filing fee has been calculated as shown below:

For	No. Filed	No. Extra	(X) LG Entity	RATE	() SM Entity	Fee
Total Claims	(31 - 20 = 11)		x	\$ 52.00	x \$ 26.00	572.00
Indep. Claims	(1 - 3 = 0)		x	\$220.00	x \$110.00	
[] Multiple Dep. Claim			+	\$390.00	+	\$195.00
* * * TOTAL FILING FEE * * *						\$ 572.00

☐ Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by month(s). The extension fee is: \$.

☒ A Check for \$572.00 is enclosed to cover fees.

☒ Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382.

TFC/smd


Terryence F. Chapman Reg. No. 32 549

CERTIFICATE OF MAILING


I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 12, 2011.

05/17/2011 JADD02 00000020 10586378

01 FC:1615

572.00 OP

130.10/08


Terryence F. Chapman

{00185968.DOC}